L	umber	Hits	Search Text	DB	Time stamp
1		3579	carrier and (solder near (ball or bump)) and (electronic or ic or chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20 18:14
2	ļ	1602	(carrier and (solder near (ball or bump)) and (electronic or ic or chip or die)) and (@ad<19990625) = = = = = = = = = = = = = = = = = = =	USPAT; US-PGPUB; EPO; JPO;	2004/07/20 18:15
3		149	((carrier and (solder near (ball or bump)) and (electronic or ic or chip or die)) and (@ad<19990625)) and 257/778.ccls.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 17:55
4		0	6515355.URPN.	USPAT	2004/07/20 16:25
5		0		USPAT	2004/07/20 16:25
6		7	("4996587" "5222014" "5569497" "5811879" "5956233" "5956605" 	USPAT	2004/07/20 _16:25
7		148	5222014.URPN.	USPAT	2004/07/20 16:33
8		5	("4672421" "4878611" "5011066" "5036431" "5060844").PN.	USPAT	2004/07/20 16:33
9		0	, , , , , , , , , , , , , , , , , , , ,	USPAT	2004/07/20 17:50
	0	1	("4959510").PN.	USPAT	2004/07/20 17:55
	2	6	((carrier and (solder near (ball or bump)) and (electronic or ic or chip or die)) and (@ad<19990625)) and ((pth or (through adj hole) or (plated near hole)) with pad) (((carrier and (solder near (ball or bump)) and (electronic or ic or chip or die)) and (@ad<19990625)) and ((pth or (through adj hole) or (plated near hole)) with pad)) and ((thick or large or big) and (small or thin or narrow or fine))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 17:56 2004/07/20 18:25
1	3	383	with pad) (semiconductor or chip or die) and (traces or trace) and (((thick or large or big) and (small or thin or narrow or fine)) with pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/20
1	4	166	((semiconductor or chip or die) and (traces or trace) and (((thick or large or big) and (small or thin or narrow or fine)) with pad)) and (@ad<19990625)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20 18:01
1	5	166	(((semiconductor or chip or die) and (traces or trace) and (((thick or large or big) and (small or thin or narrow or fine)) with pad)) and (@ad<19990625)) not 5222014.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20 18:07
1	6	64	((((semiconductor or chip or die) and (traces or trace) and (((thick or large or big) and (small or thin or narrow or fine)) with pad)) and (@ad<19990625)) not 5222014.URPN.) and carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20 18:14
1	7	23846	(chip and die) and (@ad<19990625)	USPAT; US-PGPUB; EPO; JPO;	2004/07/20 19:46
				DERWENT; IBM_TDB	

	18	15648	(solder near (ball or bump)) and	USPAT;	2004/07/20
		200.0	(electronic or ic or chip or die)	US-PGPUB;	18:15
	1		(effectionic of ic of chip of die)		10.13
	i			EPO; JPO;	
				DERWENT;	
	1			IBM TDB	1
	19	7316	((solder near (ball or bump)) and	USPAT;	2004/07/20
			(electronic or ic or chip or die)) and	US-PGPUB;	18:15
					1 10.13
			(@ad<19990625)	EPO; JPO;	
				DERWENT;	
				IBM TDB	
	-20	8	(((carrier and (solder near (ball or	USPAT;	2004/07/20
			bump)) and (electronic or ic or chip or	US-PGPUB;	18:25
			die)) and (@ad<19990625)) and ((pth or	EPO; JPO;	1 10.20
				· ·	
			(through adj hole) or (plated near hole))	DERWENT;	
			with pad)) and (((thick or large or big)	IBM_TDB	1
			and (small or thin or narrow or fine))		i i
			with (ball or balls or bump))	ĺ]
	22	0	"406198936"	JPO;	2004/07/20
			100130300	DERWENT	18:26
	22] .	"6109036"		
	23	1	"6198936"	JPO;	2004/07/20
				DERWENT	18:26
	24	2	"60198936"	JPO;	2004/07/20
				DERWENT	_18:50
	25	n	("55593666"-) PN 	USPAT	2004/07/20
				USIAI	
	ا م	_	/#57500.56#\\ ->-		18:50
	26	1	("5559366").PN.	USPAT	2004/07/20
	i				18:53
	27	1	("5939774").PN.	USPAT	2004/07/20
			, · · · · · · · · · · · · · · · · · · ·		18:54
	28	1	("6097097").PN.	USPAT	2004/07/20
i	20	*	(009/09/).PN.	OSPAI	
					18:54
	21	393	(USPAT;	2004/07/20
			(electronic or ic or chip or die)) and	US-PGPUB;	18:55
			(@ad<19990625)) and (((thick or large or	EPO; JPO;	ĺ
			big) and (small or thin or narrow or	DERWENT;	
			fine)) with (ball or balls or bump))		i
		ا ا		IBM_TDB	
	29	3	((chip and die) and (@ad<19990625)) and	USPAT;	2004/07/20
			((wireand pad) near barrier)	US-PGPUB;	19:46
				EPO; JPO;	
				DERWENT;	
				IBM TDB	
	30	0.	((chip and die) and (@ad<19990625)) and	_	2004/07/20
)		USPAT;	2004/07/20
			((wire and pad) near barrier)	US-PGPUB;	19:47
				EPO; JPO;]
				DERWENT;	į į
				IBM TDB	
	31	l ol	((chip and die) and (@ad<19990625)) and	USPAT;	2004/07/20
	· -		(pad near (barrier and wire))		
			(har wear (harrier and mire))	US-PGPUB;	19:48
				EPO; JPO;	l i
	,			DERWENT;	
	İ			IBM TDB	
	32	3	(chip or die) and (pad near (barrier and	USPAT;	2004/07/20
			wire))	US-PGPUB;	19:51
		ľ	WIIC//		19.31
				EPO; JPO;	
	-			DERWENT;	i
				IBM TDB	1
	33	0	6759597.URPN.	USPAT	2004/07/20
					19:50
	34	0	6759597.URPN.	USPAT	2004/07/20
	- T	"	0103031. UNEW.	ODPAI	
		_	(1154.66.6511) 1156.46511 : 1156.45511		19:50
	35	3	("5100835" "5249728" "5618754").PN.	USPAT	2004/07/20
ļ					19:50
	36	1	("6162664").PN.	USPAT	2004/07/20
		-	•		19:51
1		L			